



Description

The YC309 is a high performance GaAs HBT MMIC amplifier with an active bias network. The active bias network provides stable current over temperature and process Beta variations.

Designed to run directly from a 5V supply, the YC309 does not require a dropping resistor as compared to typical Darlington amplifiers.

The YC309 product is designed for high linearity 5V Gain block applications that require small size and minimal external components. It is internally matched to 50Ω.

Applications

- ◆ PA Driver Amplifier
- ◆ GSM, UMTS, LTE, 5G
- ◆ Wideband Instrumentation
- ◆ Wireless Data, Satellite Terminals

Features

- ◆ 20-4000MHz
- ◆ OIP3=39.7dBm @900MHz
- ◆ P1dB=23.5dBm @900MHz
- ◆ Gain=22.5dB @900MHz
- ◆ Internally matched to 50Ω
- ◆ SOT-89 Package
- ◆ RoHS Compliant/Lead-free

Electrical Specification

Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Gain	21.5	22.5		900MHz	dB
	17.0	18.0		1900MHz	dB
	16.2	17.2		2100MHz	dB
Output P1dB	22.5	23.5		900MHz	dBm
	22.3	23.3		1900MHz	dBm
	22.1	23.1		2100MHz	dBm
Output IP3	37.7	39.7		900MHz	dBm
	36.9	38.9		1900MHz	dBm
	36.0	38.0		2100MHz	dBm
Input Return Loss	-18.3	-16.3		900MHz	dB
Output Return Loss	-13.7	-11.7		900MHz	dB
Reverse Isolation	-28.7	-26.7		900MHz	dB
Noise Figure		3.1	3.6	900MHz	dB
Device Voltage		5.0			V
Device Current		87			mA
Thermal Resistance		48.6			°C/W

Notes:

1) Test conditions: VCC = +5 V, Temp. = +25 °C, Zo=50Ω, OIP3:Pout = +9 dBm/tone, Δf = 1 MHz

Recommended Operating Condition

Parameter	Min	Typ	Max	Units
Device Voltage		5		V
Operating Temperature	-40	25	85	°C
Junction Temperature	-		164	°C

Absolute Maximum Ratings

Parameter	Rating	Units
Device Voltage	6	V
Supply Current	133	mA
Storage Temperature	-55~+155	°C
RF Input Power	23	dBm

Typical RF Performance

Frequency(MHz)	900	1900	2100	2400	3500	Units
Gain	22.5	18.0	17.2	16.1	13.5	dB
S11	-16.3	-28.4	-33.1	-18.9	-19.0	dB
S22	-11.7	-11.6	-12.0	-12.6	-13.4	dB
S12	-26.7	-24.9	-24.2	-24.3	-21.9	dB
Output P1dB	25.4	24.7	24.7	25.9	24.8	dBm
Output IP3	40.0	40.1	40.6	39.9	38.3	dBm
Noise Figure	3.1	3.7	3.5	3.4	4.0	dB

MSL Rating

MSL Rating : Level 3
 Test : 260°C Convection Reflow
 Standard : JEDEC Standard IPC/JEDEC J-STD-020

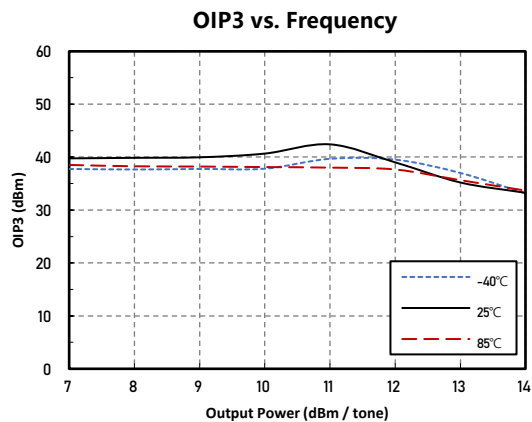
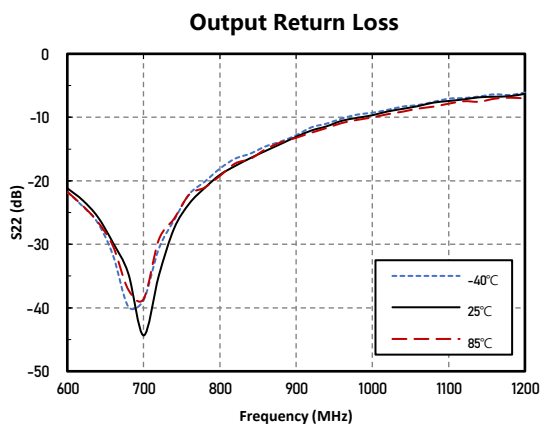
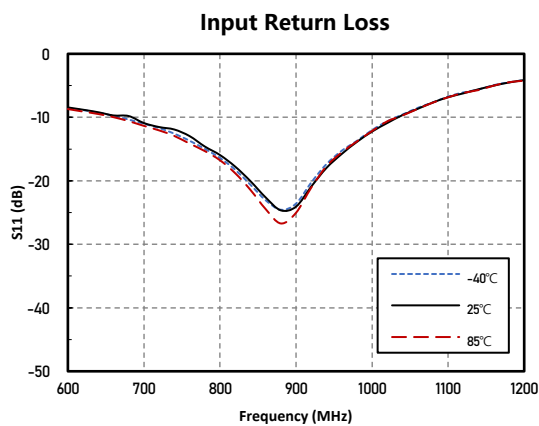
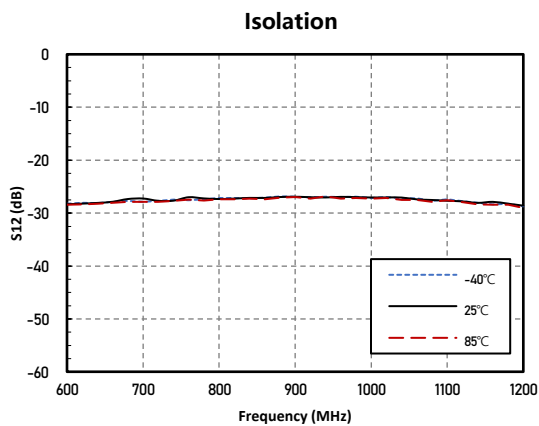
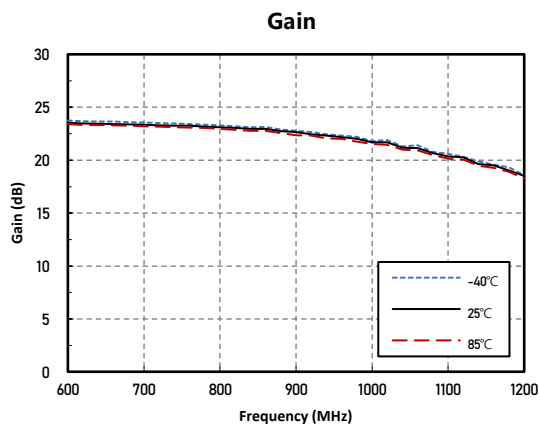
ESD Sensitivity Ratings

ESD Rating : Class 1C
 Test : Human Body Model (HBM)
 Standard : JEDEC Standard JS-001-2012



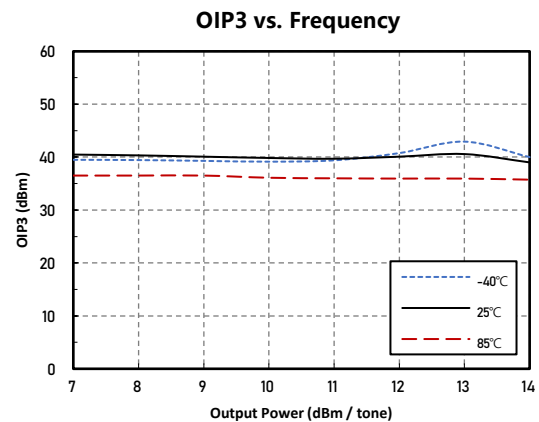
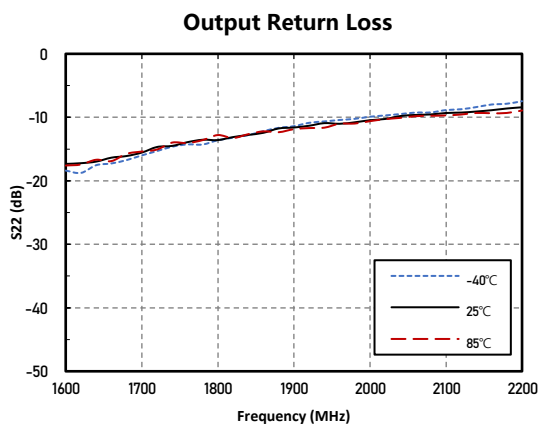
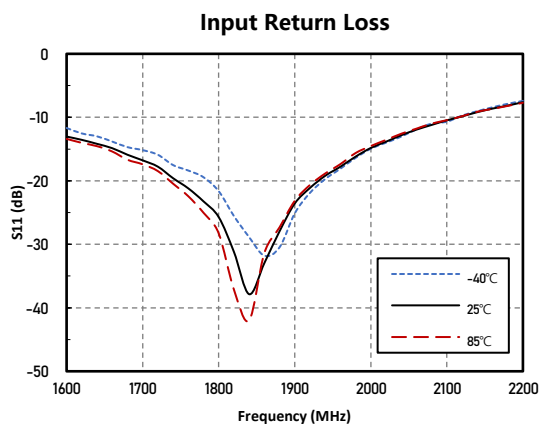
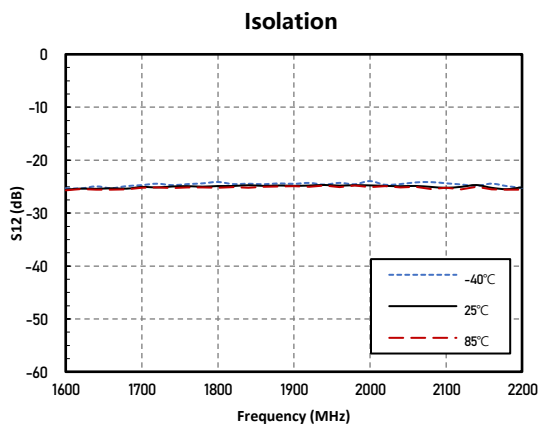
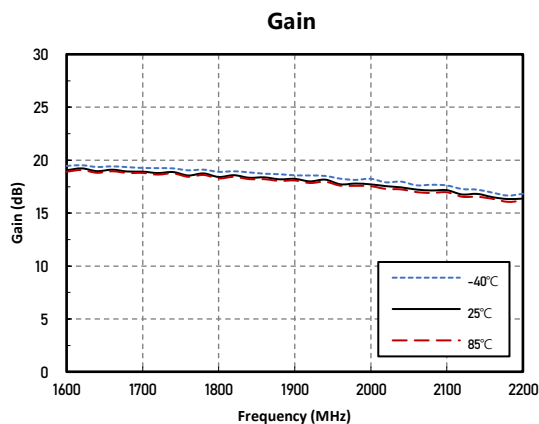
Performance Plots

$V_{CC} = +5V$, $I_C = 87mA$, $T = 25^{\circ}C$, $Freq = 600 \sim 1200$ MHz, $Z_O = 50\Omega$



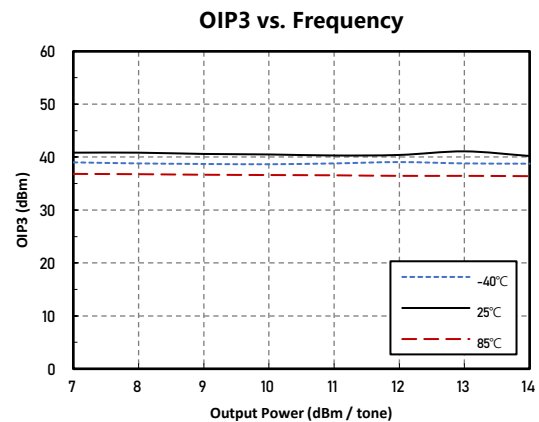
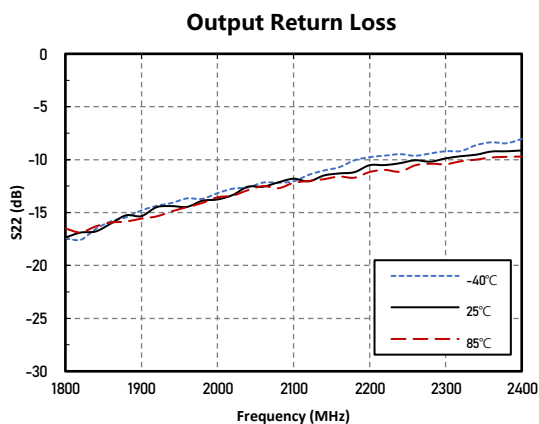
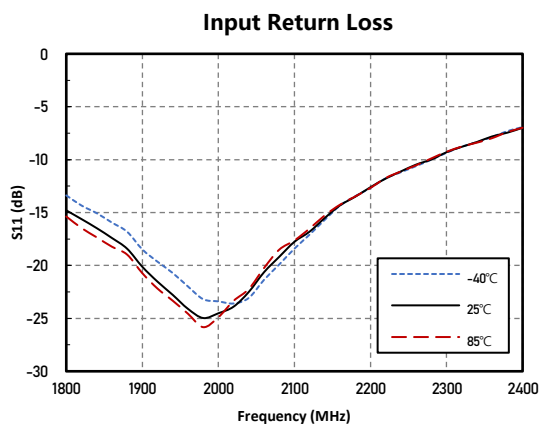
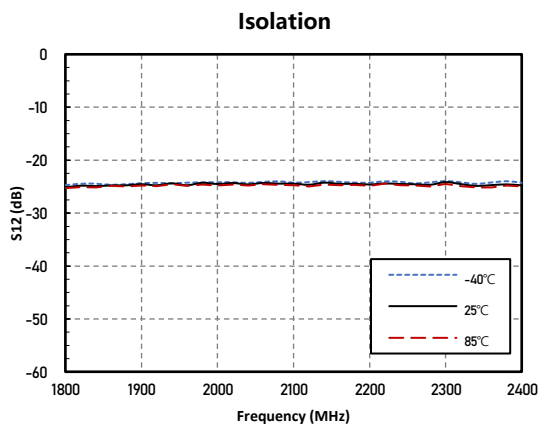
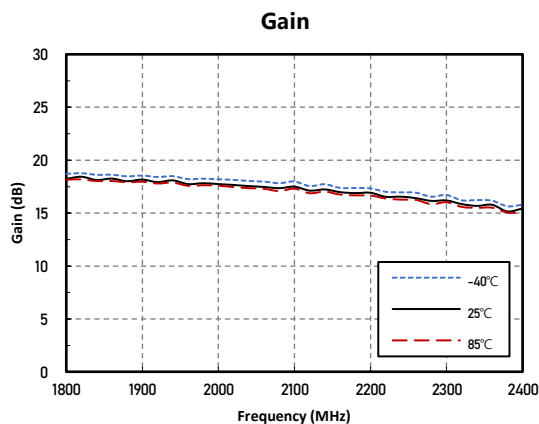
Performance Plots

$V_{CC} = +5V$, $I_C = 87mA$, $T = 25^{\circ}C$, $Freq = 1600 \sim 2200$ MHz, $Z_O = 50\Omega$



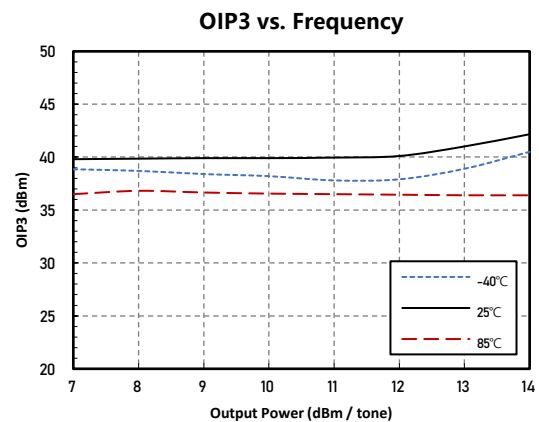
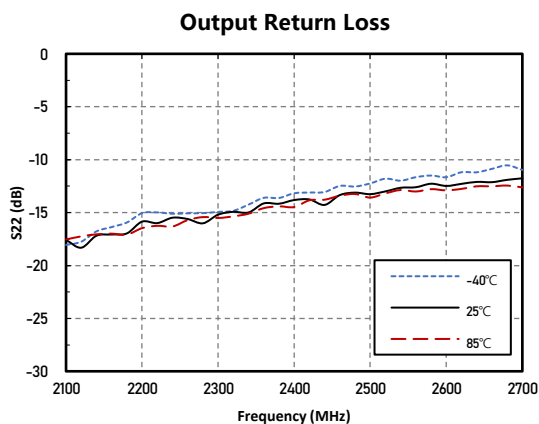
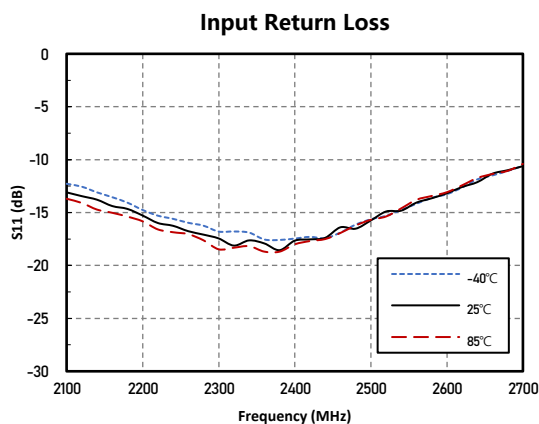
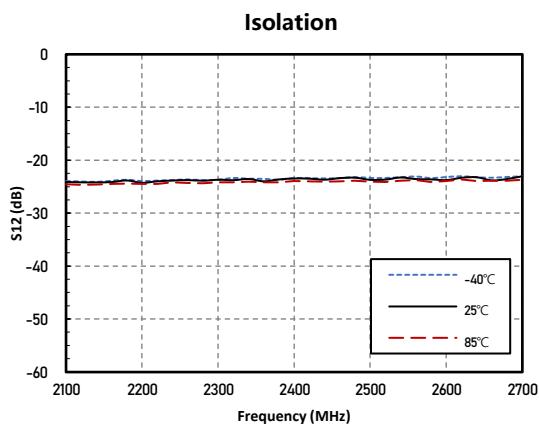
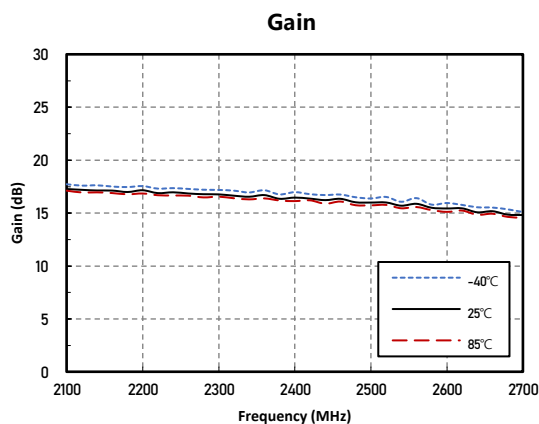
Performance Plots

$V_{CC} = +5V$, $I_C = 87mA$, $T = 25^\circ C$, $Freq = 1800 \sim 2400$ MHz, $Z_O = 50\Omega$



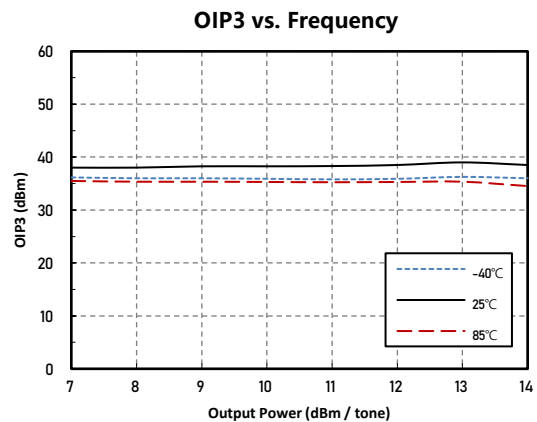
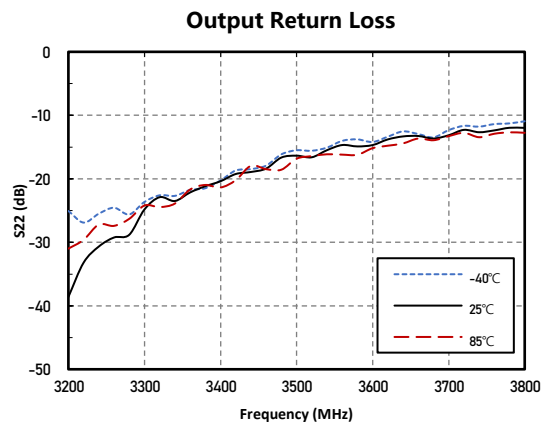
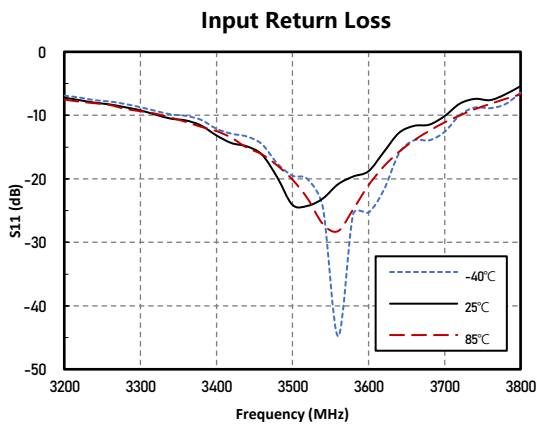
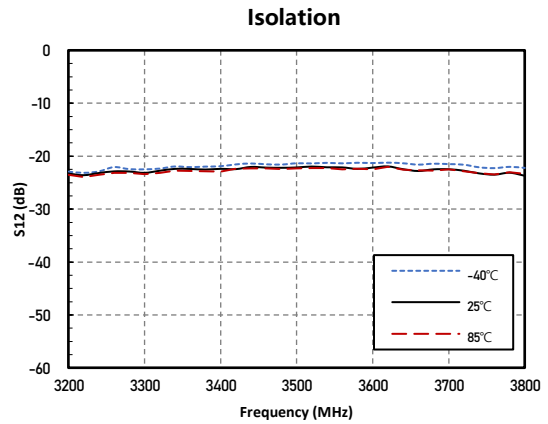
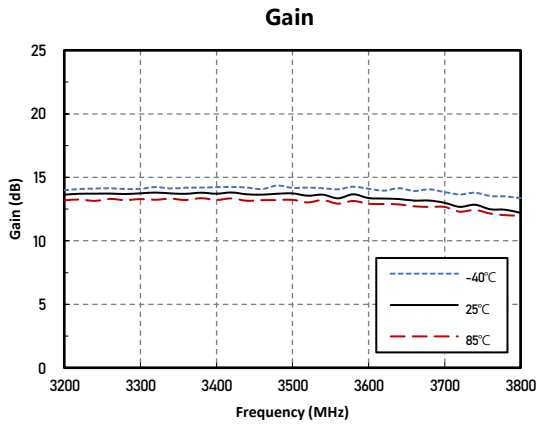
Performance Plots

$V_{CC} = +5V$, $I_C = 87mA$, $T = 25^{\circ}C$, $Freq = 2100 \sim 2700$ MHz, $Z_O = 50\Omega$



Performance Plots

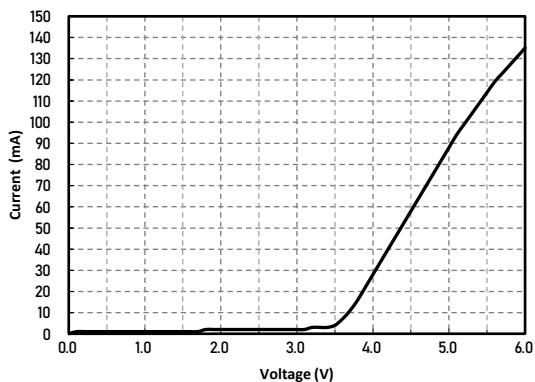
$V_{CC} = +5V$, $I_C = 87mA$, $T = 25^\circ C$, $Freq = 3200 \sim 3800$ MHz, $Z_O = 50\Omega$



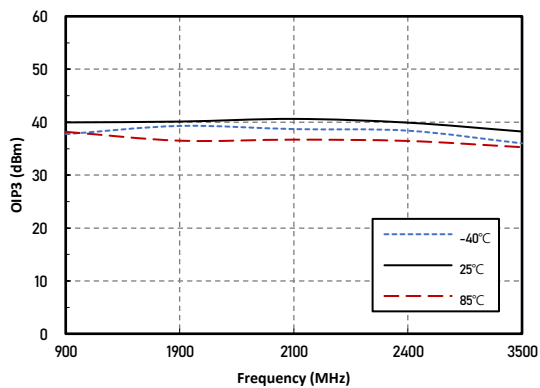
Performance Plots

$V_{CC} = +5V$, $I_C = 87mA$, $T = 25^\circ C$, $Z_O = 50\Omega$

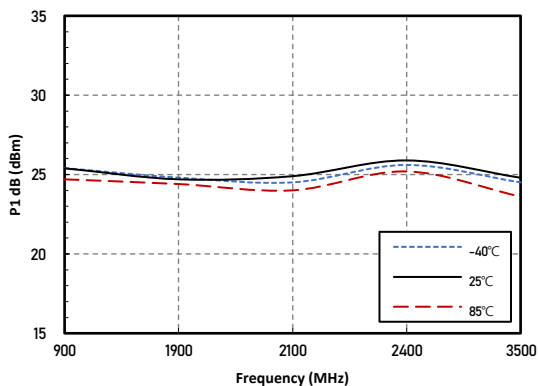
I-V Curve



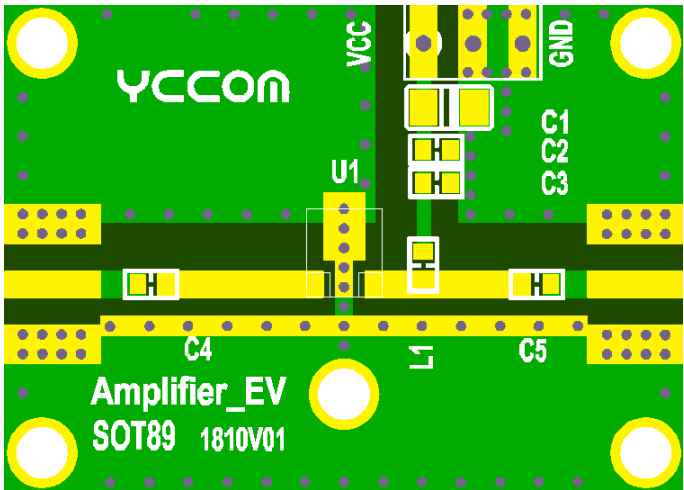
OIP3 vs. Frequency ($P_{OUT} : 9dBm/ton$)



P1dB vs. Frequency

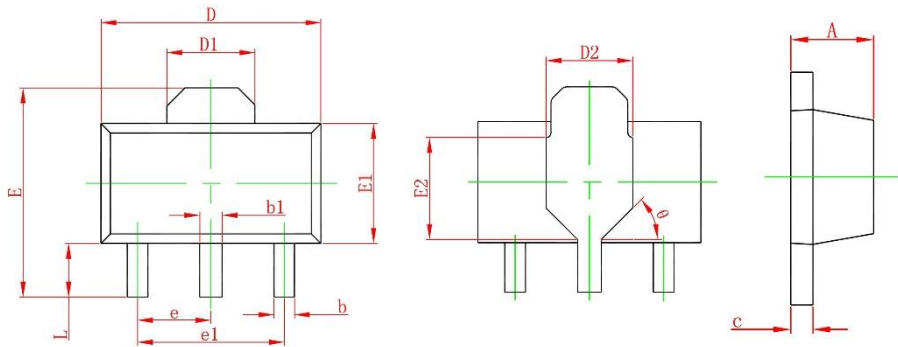


Evaluation Board PCB Information



- ① PCB: FR4 ② RF width: 1.34 mm ③ PCB thick: 0.8 mm

Package Outline Drawing

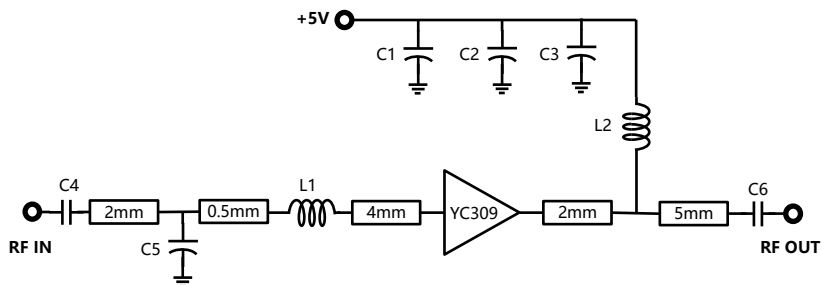


SOT-89		
Symbol	Min	Max
A	1.400	1.600
b	0.320	0.520
b1	0.380	0.580
c	0.350	0.440
D	4.400	4.600
D1	1.550 REF.	
D2	1.750 REF.	
E	3.940	4.250
E1	2.300	2.600
E2	1.900 REF.	
e	1.500 TYP.	
e1	3.000 TYP.	
L	0.900	1.200
θ	45°	
All Dimensions in mm		

Application Circuit

Freq = 600 ~ 1200 MHz

Schematic Diagram



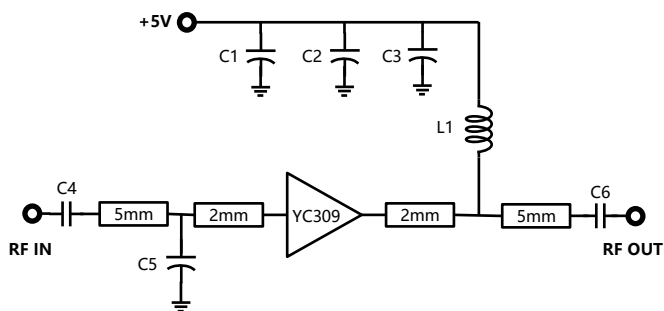
BOM	Tolerance
C1	None.
C2	1nF ±5%
C3	100pF ±5%
C4	100pF ±5%
C5	4.3pF ±5%
C6	100pF ±5%
L1	2.7nH ±5%
L2	39nH ±5%

Note

1. Distance between the input pin of YC309 and the center of the series inductor(L1) is **4mm**.
2. Distance between the center of the series inductor(L1) and the center of the shunt cap(C5) is **0.5mm**.
3. Distance between the center of the shunt cap(C5) and the center of the series cap(C4) is **2mm**.
4. Distance between the output pin of YC309 and the center of the shunt inductor(L2) is **2mm**.
5. Distance between the center of the shunt inductor(L2) and the center of the series cap(C6) is **5mm**.

Freq = 1600 ~ 2200 MHz

Schematic Diagram



BOM	Tolerance
C1	None.
C2	1nF ±5%
C3	100pF ±5%
C4	33pF ±5%
C5	1.8pF ±5%
C6	33pF ±5%
L1	27nH ±5%

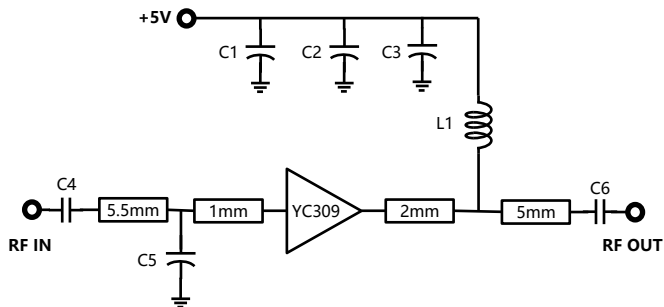
Note

1. Distance between the input pin of YC309 and the center of the shunt cap(C5) is **2mm**.
2. Distance between the center of the shunt cap(C5) and the center of the series cap(C4) is **5mm**.
3. Distance between the output pin of YC309 and the center of the shunt inductor(L1) is **2mm**.
4. Distance between the center of the shunt inductor(L1) and the center of the series cap(C6) is **5mm**.

Application Circuit

Freq = 1800 ~ 2400 MHz

Schematic Diagram



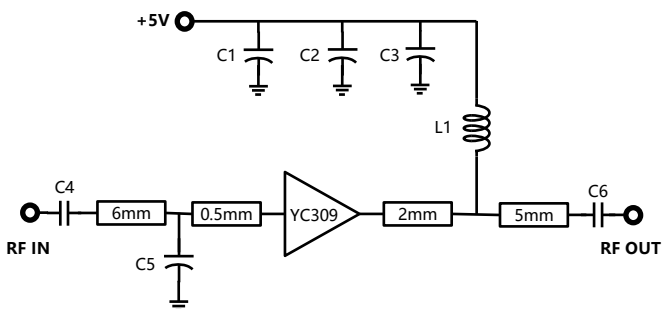
BOM	Tolerance	
C1	None.	
C2	1nF	±5%
C3	100pF	±5%
C4	33pF	±5%
C5	1.5pF	±5%
C6	33pF	±5%
L1	18nH	±5%

Note

1. Distance between the input pin of YC309 and the center of the shunt cap(C5) is **1mm**.
2. Distance between the center of the shunt cap(C5) and the center of the series cap(C4) is **5.5mm**.
3. Distance between the output pin of YC309 and the center of the shunt inductor(L1) is **2mm**.
4. Distance between the center of the shunt inductor(L1) and the center of the series cap(C6) is **5mm**.

Freq = 2100 ~ 2700 MHz

Schematic Diagram



BOM	Tolerance	
C1	None.	
C2	1nF	±5%
C3	100pF	±5%
C4	33pF	±5%
C5	1.2pF	±5%
C6	33pF	±5%
L1	18nH	±5%

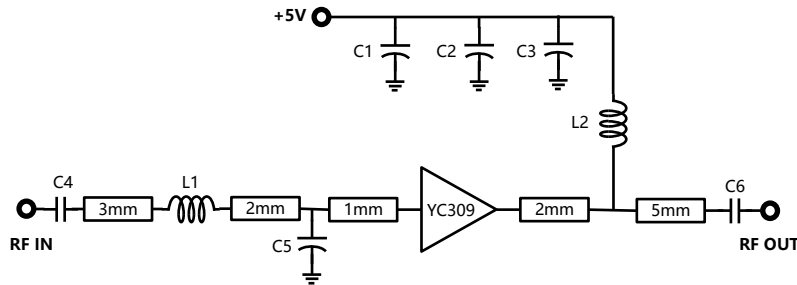
Note

1. Distance between the input pin of YC309 and the center of the shunt cap(C5) is **0.5mm**.
2. Distance between the center of the shunt cap(C5) and the center of the series cap(C4) is **6mm**.
3. Distance between the output pin of YC309 and the center of the shunt inductor(L1) is **2mm**.
4. Distance between the center of the shunt inductor(L1) and the center of the series cap(C6) is **5mm**.

Application Circuit

Freq = 3200 ~ 3800 MHz

Schematic Diagram

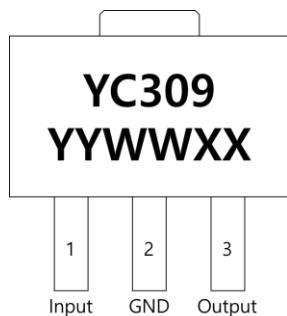


BOM		Tolerance
C1		None
C2	1nF	±5%
C3		None
C4	33pF	±5%
C5	0.5pF	±5%
C6	33pF	±5%
L1	3.3nH	±5%
L2	18nH	±5%

Note

1. Distance between the input pin of YC309 and the center of the series inductor(L1) is **1mm**.
2. Distance between the center of the series inductor(L1) and the center of the shunt cap(C5) is **2mm**.
3. Distance between the center of the shunt cap(C5) and the center of the series cap(C4) is **3mm**.
4. Distance between the output pin of YC309 and the center of the shunt inductor(L2) is **2mm**.
5. Distance between the center of the shunt inductor(L2) and the center of the series cap(C6) is **5mm**.

Package Marking



P/N : YC309
 YY : Year
 WW : Week
 XX : Wafer No.

PCB Land Pattern

